Vishay Semiconductors



Molding Type Module IGBT, 2-in-1 Package, 1200 V, 400 A



Double	INT-A-PAK
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PRODUCT SUMMARY			
V _{CES}	1200 V		
I_C at T_C = 80 °C	400 A		
$V_{CE(on)}$ (typical) at I _C = 400 A, 25 °C	1.90 V		
Speed	8 kHz to 30 kHz		
Package	Double INT-A-PAK		
Circuit	Half bridge		

FEATURES

- Low V_{CE(on)} trench IGBT technology
- 10 µs short circuit capability
- V_{CE(on)} with positive temperature coefficient
- Maximum junction temperature 175 °C
- Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

- Inverter for motor drive
- · AC and DC servo drive amplifier
- Uninterruptible power supply (UPS)

DESCRIPTION

Vishay's IGBT power module provides ultralow conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \text{ °C}$ unless otherwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V _{CES}		1200	V
Gate to emitter voltage	V _{GES}		± 30	v
Collector current	I _C	T _C = 25 °C	750	
		T _C = 80 °C	400	
Pulsed collector current	I _{CM}	t _p = 1 ms	800	А
Diode continuous forward current	١ _F		400	
Diode maximum forward current	I _{FM}	t _p = 1 ms	800	
Maximum power dissipation	PD	T _J = 175 °C	2344	W
RMS isolation voltage	V _{ISOL}	f = 50 Hz, t = 1 min	2500	V
Operating junction temperature range	TJ		-40 to +150	°C



COMPLIANT



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IGBT ELECTRICAL SPECIFICATIONS ($T_c = 25 \text{ °C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V _{(BR)CES}	T _J = 25 °C	1200	-	-	
Collector to emitter voltage	V _{CE(on)}	V_{GE} = 15 V, I_C = 400 A, T_J = 25 °C	-	1.90	2.35	v
Collector to enlitter voltage		$V_{GE} = 15 \text{ V}, \text{ I}_{C} = 400 \text{ A}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	2.30	-	v
Gate to emitter threshold voltage	V _{GE(th)}	V_{CE} = V_{GE} , I_C = 20 mA, T_J = 25 °C	5.0	5.9	7.5	
Collector cut-off current	I _{CES}	$V_{CE} = V_{CES}, V_{GE} = 0 \text{ V}, \text{T}_{\text{J}} = 25 ^{\circ}\text{C}$	-	-	5.0	mA
Gate to emitter leakage current	I _{GES}	$V_{GE}=V_{GES},V_{CE}=0~V,T_J=25~^\circ C$	-	-	400	nA

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t _{d(on)}		-	187	-	
Rise time	t _r		-	57	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, \text{ I}_{C} = 400 \text{ A}, \text{ R}_{g} = 1.4 \Omega,$	-	180	-	ns
Fall time	t _f	V _{GE} = ± 15 V, T _J = 25 °C	-	149	-	
Turn-on switching loss	E _{on}		-	19.9	-	mJ
Turn-off switching loss	E _{off}		-	18.8	-	
Turn-on delay time	t _{d(on)}		-	189	-	- ns
Rise time	tr		-	58	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, \text{ I}_{C} = 400 \text{ A}, \text{ R}_{g} = 1.4 \Omega,$	-	187	-	
Fall time	t _f	V _{GE} = ± 15 V, T _J = 125 °C	-	220	-	
Turn-on switching loss	E _{on}		-	31.2	-	
Turn-off switching loss	E _{off}		-	23.4	-	mJ
Input capacitance	C _{ies}		-	51.2	-	
Output capacitance	C _{oes}	V _{GE} = 0 V, V _{CE} = 30 V, f = 1.0 MHz	-	1.84	-	nF
Reverse transfer capacitance	C _{res}		-	1.28	-	
SC data	I _{SC}	$ \begin{array}{l} t_p \leq 10 \; \mu s, V_{GE} = 15 \; V, T_J = 125 \; ^{\circ}C, \\ V_{CC} = 900 \; V, V_{CEM} \leq 1200 \; V \end{array} $	-	3560	-	А
Internal gate resistance	R _{gint}		-	0.59	-	Ω
Stray inductance	L _{CE}		-	-	18	nH
Module lead resistance, terminal to chip	R _{CC'+EE'}		-	0.32	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS ($T_C = 25$ °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITION	TEST CONDITIONS		TYP.	MAX.	UNITS
Diode forward voltage	¥-	I _F = 400 A	T _J = 25 °C	-	1.80	2.20	v
Dide forward voltage	V _F	IF = 400 A	T _J = 125 °C	-	1.85	-	v
Papayany charge	Q _{rr}	Q _{rr}	T _J = 25 °C	-	26	-	
Recovery charge			T _J = 125 °C	-	49	-	μC
Deels reverse receivery ourrent	$I_{rr} \qquad I_F = 400 \text{ A}, V_R = 600 \text{ V}, \\ R_g = 4.1 \Omega, V_{\text{GE}} = -15 \text{ V} \\ \end{cases}$	T _J = 25 °C	-	212	-	^	
Peak reverse recovery current		R_g = 4.1 Ω , V_{GE} = -15 V	T _J = 125 °C	-	281	-	A
	E _{rec}		T _J = 25 °C	-	23.4	-	ml
Reverse recovery energy			T _J = 125 °C	-	33.8	-	mJ

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THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction temperature	T _J max.		-	-	175	
Operating junction temperature rar	nge T _{Jop}		-40	-	150	°C
Storage temperature range	T _{STG}		-40	-	125	
Junction to case	iBT		-	-	0.064	
	ode R _{thJC}		-	-	0.098	K/W
Case to sink	R _{thCS}	Conductive grease applied	-	0.032	-	
Mounting torque		Power terminal screw: M6		2.5 to 5.0)	Nm
Mounting torque		Mounting screw: M6		3.0 to 5.0)	
Weight				350		g







Fig. 2 - IGBT Transfer Characteristics



Fig. 3 - IGBT Switching Loss vs. $\rm I_{C}$



Fig. 4 - IGBT Switching Loss vs. Rg

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Fig. 5 - RBSOA







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Fig. 8 - Diode Switching Loss vs. IF

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Fig. 9 - Diode Switching Loss vs. Rg



Fig. 10 - Diode Transient Thermal Impedances

CIRCUIT CONFIGURATION



LINKS TO RELATED DOCUMENTS			
Dimensions	www.vishay.com/doc?95538		



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Double INT-A-PAK

DIMENSIONS in millimeters (inches)





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